3rd IEEE International Workshop on

Automated Test Equipment: ATE Vision 2020

Moscone Center, San Francisco, USA

July 15, 2010

Held in conjunction with SEMICON West 2010

Call for Papers

Scope: As in years past, this workshop will examine where the ATE industry is heading. Moore's law continues to move forward with denser, large, faster, and highly heterogeneous devices coming our way. Further complications to this situation are the challenges associated with multiple cores on a die and the 3D trends enabled by die-stacking and thru-silicon-vias.

These issues, when added to ever increasing test complexity, cost-of-test, and time-to-market pressures, pose a significant challenge to the ATE industry. To meet these challenges the industry (ATE developers and end-users together) need to innovate in areas such as: shared interconnect technology, streamlined test program generation methods, and better integrated DFT tools.

The goal of this workshop is to create an informal forum to discuss those innovations relevant to ATE developers and users. We are looking for solutions and ideas for solutions to the issues we have in our future. What do we need to do differently? What will an ATE need to look like in 2015 and 2020? Are our present technologies adequate for the future and if not what should we be doing to close the gap?

This workshop is unique. We're not necessarily looking for a standard paper filled with results; we are looking for speculation and creative brainstorming ideas. Let's challenge ourselves and each other.

Representative topics include, but are not limited to:

- Critical "future-proof" ATE capabilities
- Test methods for future defects
- 3D device testing ideas and techniques
- Power testing needs for 'green' technology
- Protocol aware techniques
- High-speed IO Test
- Insuring test quality while minimizing test cost
- RF and SOC testing trends
- Adaptive & concurrent testing challenges
- Test program generation ideas
- Ways to streamline our test efforts
- Killer ATE product ideas

Author information:

To present at the workshop, authors are invited to submit presentation proposals. The proposals may be draft presentations, extended abstracts (500 words), or full papers. Each submission should include: title, full name and affiliation of all authors, a short abstract of 50 words, and keywords. Also, identify a contact author and include a complete correspondence address, phone, fax and e-mail.

In addition to traditional 20-30 minute presentations we are also looking this year for some quick 5-10 minute elevator-pitch presentations. These would be an ideal opportunity to pitch a new product idea to a team of mock venture-capitalists in order to explore (in fun) the potential value of your product concept.

Submit a copy of your presentation proposal by Postscript, or PDF, via E-mail. Proposals for panel discussions are also invited. Submissions are due no later than **May 7, 2010**. Submit your proposals to:

Dave Armstrong, Advantest, E-mail: **d.armstrong@advantest.com** Tel: +1-303-665-5227

Authors will be notified of the disposition of their presentation by **June 4, 2010** and must submit the final presentation by **June 18, 2010** for inclusion in the Workshop Notes, which will be provided to the attendees on a memory stick. Optionally, an extended abstract/paper can be included in the notes.

The ATE Vision 2020 Workshop is sponsored by the IEEE Computer Society Test Technology Technical Council (TTTC).

More information available at: www.ATEVision.com

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